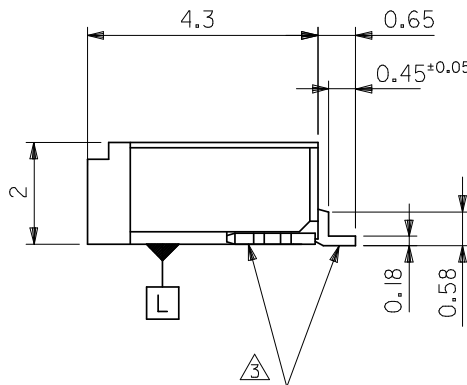
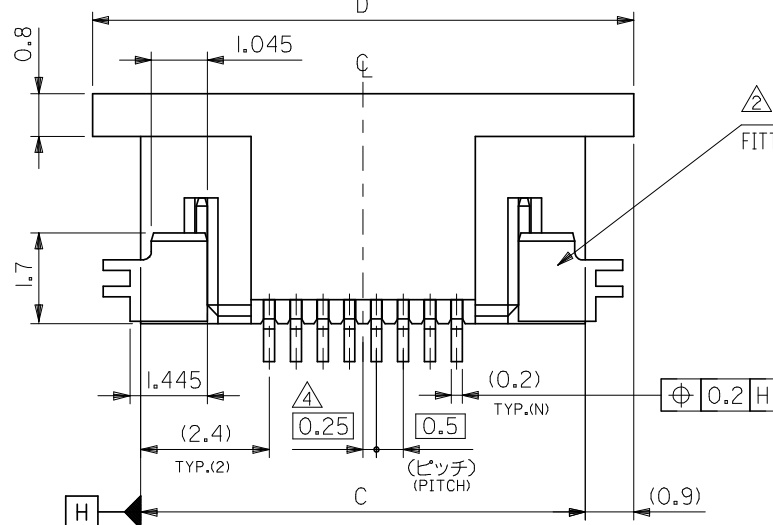
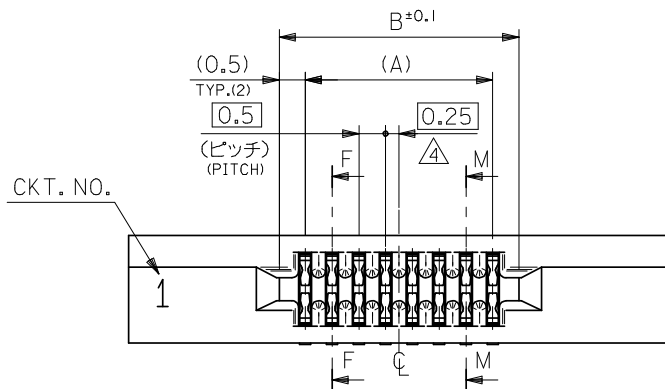
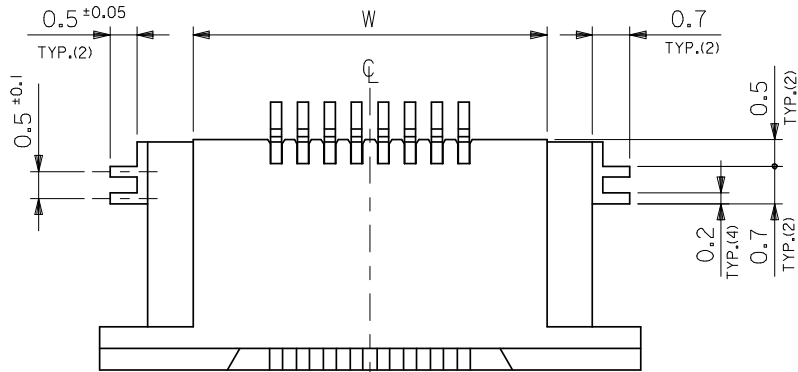
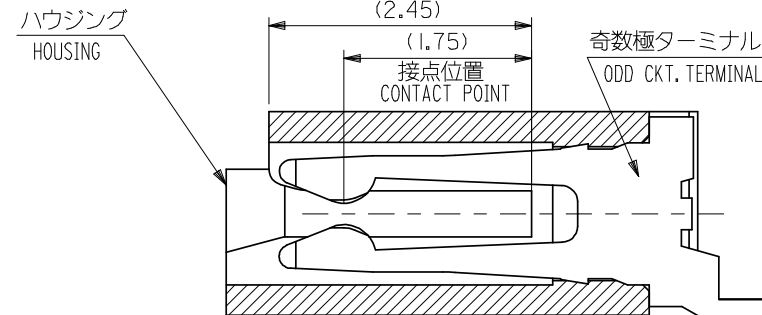


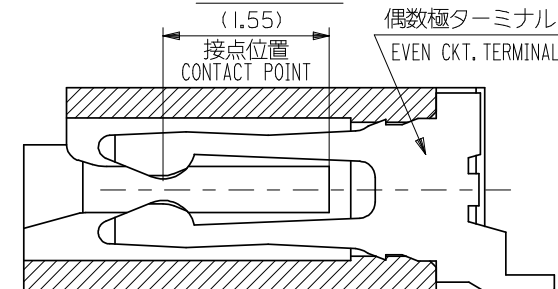
10 9 8 7 6 5 4 3 2 1



△金具
FITTING NAIL



SECT. M-M



SECT. F-F

注記(NOTES)

1. 使用材料 (MATERIAL)

ターミナル (TERMINAL): リン青銅

PHOSPHOR BRONZE ±0.2

錫ビスマスメッキ 1. 0マイクロメートル以上

TIN-BISMUTH I.O. MICROMETER MINIMUM

ニッケル下地 1. 0マイクロメートル以上

NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM

ハウジング (HOUSING): 46ナイロン (46NYLON), UL94V-0

金具 (FITTING NAIL): リン青銅

PHOSPHOR BRONZE ±0.2

錫メッキ 1. 0マイクロメートル以上

TIN I.O. MICROMETER MINIMUM

ニッケル下地 1. 0マイクロメートル以上

NICKEL (UNDER PLATING) I.O. MICROMETER MINIMUM

△ パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB. PATTERN.)

ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L に対し上方向 0.1MAX. 下方向 0.15MAX. とする。

MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L

UPPER DIRECTION 0.1MAX., LOWER DIRECTION 0.15MAX.

偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)

5. 本製品は 52689-***40 の鉛フリー品である。

THIS PRODUCT IS LEAD FREE 52689-***40.

MODEL NO. 52689-***49

GENERAL TOLERANCES
(UNLESS SPECIFIED)

DIMENSION STYLE
MM ONLY

SCALE

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

10 UNDER ±0.2

10 OVER 30 UNDER ±0.25

30 OVER ±0.3

ANGULAR ±3 °

DRAFT WHERE APPLICABLE

MUST REMAIN

WITHIN DIMENSIONS

DRAWN BY DATE

H. KAWABATA '04/02/03

CHECKED BY DATE

K. TOJO '04/02/03

APPROVED BY DATE

M. SASAO '04/02/03

MATERIAL NO.

SEE SHEET 2

TITLE

0.5 FPC CONN NON ZIF
HSG ASSY FOR SMT(R/A)
-LEAD FREE-

molex

MOLEX INCORPORATED

DOCUMENT NO.

SD-52689-034

SHEET NO.

1 OF 2

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

F

E

D

C

B

A

F

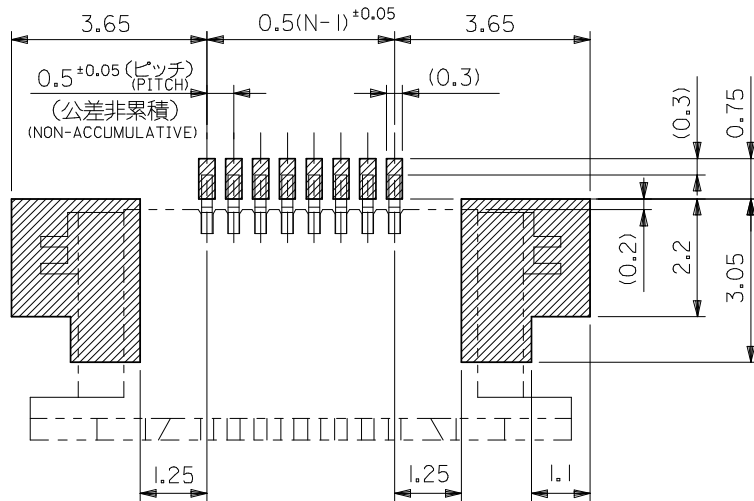
E

D

C

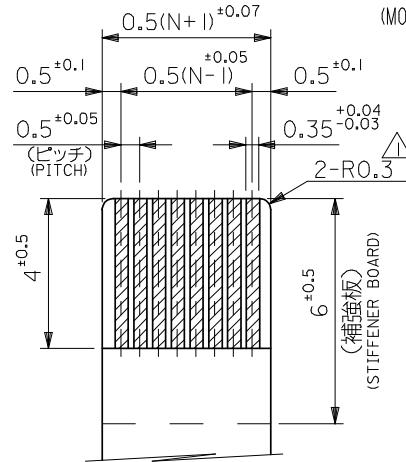
B

A



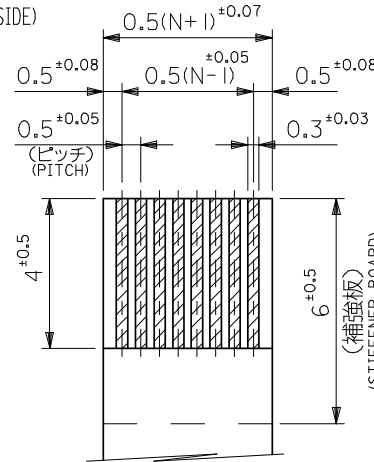
参考基板レイアウト
(マウント面)

REFERENCE P.C. BOARD
PATTERN DIMENSION
(MOUNTING SIDE)



適合F P C推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合F F C推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

F P Cについて:
打抜き方向は導体側から補強板側を推奨致します。
補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION : FORM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

注記 NOTES

- △ R0.3は、F P Cの導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.

17.6	21.1	19.3	15.5	14.5	52689-3087	52689-3049	30
17.1	20.6	18.8	15.0	14.0	-2987	-2949	29
16.6	20.1	18.3	14.5	13.5	-2887	-2849	28
16.1	19.6	17.8	14.0	13.0	-2787	-2749	27
15.6	19.1	17.3	13.5	12.5	-2687	-2649	26
15.1	18.6	16.8	13.0	12.0	-2587	-2549	25
14.6	18.1	16.3	12.5	11.5	-2487	-2449	24
14.1	17.6	15.8	12.0	11.0	-2387	-2349	23
13.6	17.1	15.3	11.5	10.5	-2287	-2249	22
13.1	16.6	14.8	11.0	10.0	-2187	-2149	21
12.6	16.1	14.3	10.5	9.5	-2087	-2049	20
12.1	15.6	13.8	10.0	9.0	-1987	-1949	19
11.6	15.1	13.3	9.5	8.5	-1887	-1849	18
11.1	14.6	12.8	9.0	8.0	-1787	-1749	17
10.6	14.1	12.3	8.5	7.5	-1687	-1649	16
10.1	13.6	11.8	8.0	7.0	-1587	-1549	15
9.6	13.1	11.3	7.5	6.5	-1487	-1449	14
9.1	12.6	10.8	7.0	6.0	-1387	-1349	13
8.6	12.1	10.3	6.5	5.5	-1287	-1249	12
8.1	11.6	9.8	6.0	5.0	-1187	-1149	11
7.6	11.1	9.3	5.5	4.5	-1087	-1049	10
7.1	10.6	8.8	5.0	4.0	-0987	-0949	9
6.6	10.1	8.3	4.5	3.5	-0887	-0849	8
6.1	9.6	7.8	4.0	3.0	-0787	-0749	7
5.6	9.1	7.3	3.5	2.5	-0687	-0649	6
5.1	8.6	6.8	3.0	2.0	52689-0587	52689-0549	5

52689-***49	W	D	C	B	A	EMBOSSED TAPE	MATERIAL NO.	極数 CKT.
MODEL NO.						ORDER No. オーダー番号		

REVISED EC NO: J2008-4308 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA REV B	2008/06/27 2008/06/30 2008/06/30		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	DESCRIPTION		10 UNDER ±0.2		DRAWN BY H. KAWABATA		DATE '04/02/03		TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT(R/A) -LEAD FREE- MOLEX MOLEX INCORPORATED	
			10 OVER 30 UNDER ±0.25		CHECKED BY K. TOJO		DATE '04/02/03			
			30 OVER ±0.3		APPROVED BY M. SASAO		DATE '04/02/03			
			ANGULAR ±3 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52689-034			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
REV		SHEET NO. 2 OF 2								

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

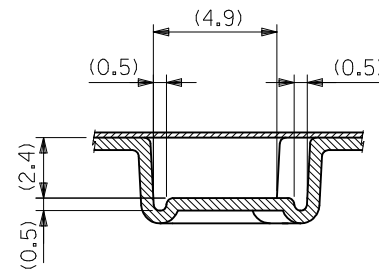
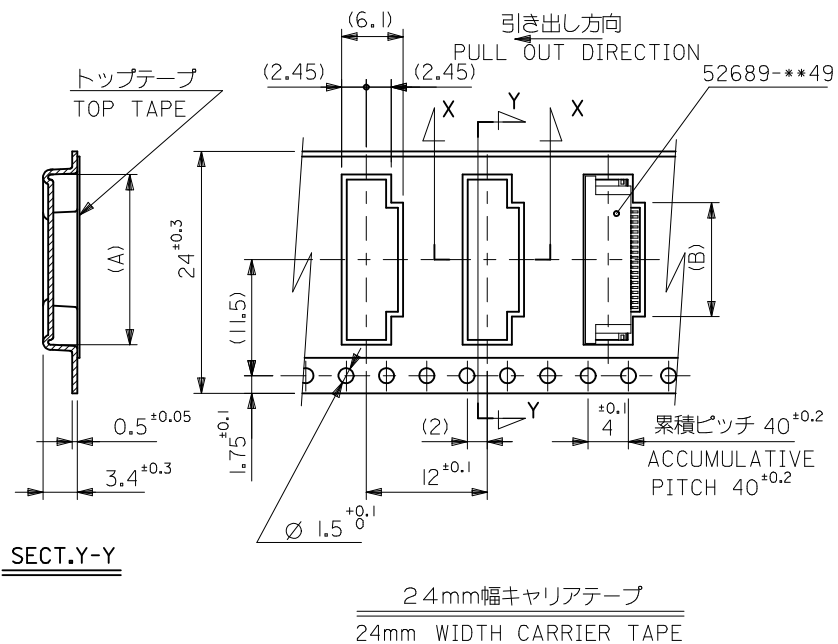
E

D

C

B

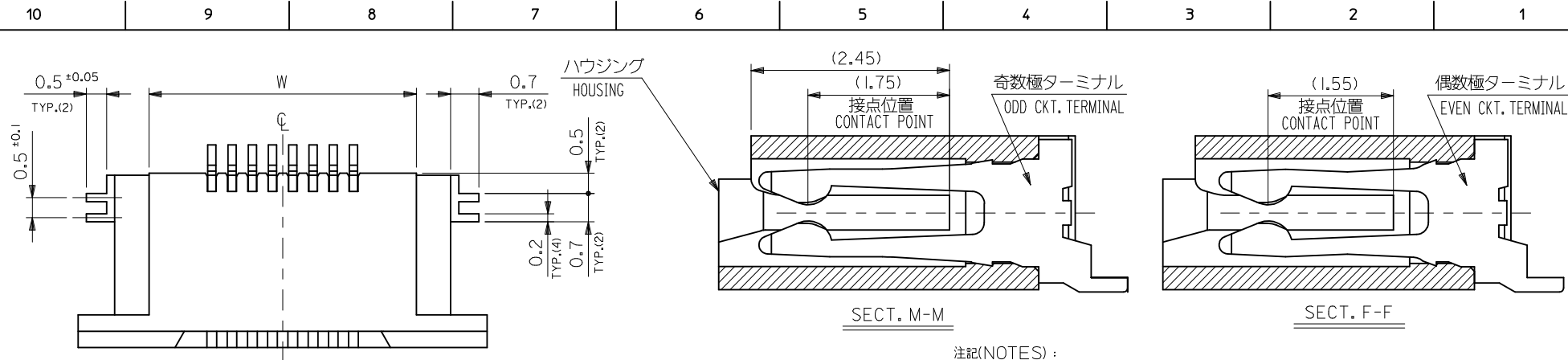
A



SECT.X-X

24	29.4	25.4	11.8	17.4	52689-2287	22
52689-***87	キャリアテープ幅	E	D	(B)	(A)	MATERIAL NO.
MODEL NO.	CARRIER TAPE WIDTH					極数 CIRCUIT

REVISED EC NO: J2009-2061 2009/05/20 DRWN:TKON CHKD:HMATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21 A	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION								
		10 UNDER		DRAWN BY H.KAWABATA	DATE 2004/02/03	TITLE 0.5 FPC CONN NON ZIF HSG ASSY SMT RA EMBSTP PKG -LEAD FREE-										
		10 OVER 30 UNDER		CHECKED BY K. TOJO	DATE 2004/02/03											
		30 OVER		APPROVED BY M. SASAO	DATE 2004/02/03	MOLEX INCORPORATED										
		ANGULAR		MATERIAL NO.							DOCUMENT NO.					SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE							SD-52689-035					3 OF 3
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													



SECT. M-M

SECT. F-F

注記(NOTES):

1. 使用材料 MATERIAL

ターミナル : リン青銅 (t=0.2)

TERMINAL : PHOSPHOR BRONZE t=0.2

ハウジング : 46ナイロン, ナチュラル, ガラス充填, UL94V-0

HOUSING : 46NYLON, NATURAL, GLASS FILLED, UL94V-0

金具 : リン青銅 (t=0.2)

FITTING NAIL : PHOSPHOR BRONZE t=0.2

2. めっき仕様 PLATING

ターミナル TERMINAL

錫銀ヒスマスメッキ (1.0 μm以上)

TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)

下地: ニッケルめっき (1.0 μm以上)

UNDER PLATE: NICKEL PLATING (1.0 MICROMETER MINIMUM)

金具 FITTING NAIL

錫系メッキ (1.0 μm以上)

TIN BASED PLATE (1.0 MICROMETER MINIMUM)

下地: ニッケルめっき (1.0 μm以上)

UNDER PLATE: NICKEL (1.0 MICROMETER MINIMUM)

3. パターン剥離止め用金具

FITTING NAIL FOR PREVENTION OF PEELING OFF PCB.PATTERN.

4.

溶剤テール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 L

に対し上方向0.1MAX, 下方向0.15MAXとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM L
UPPER DIRECTION 0.1MAX, LOWER DIRECTION 0.15MAX.

5. 偶数極に適用。

TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.

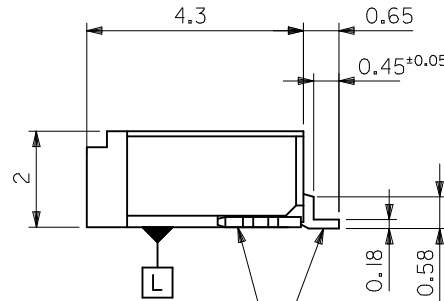
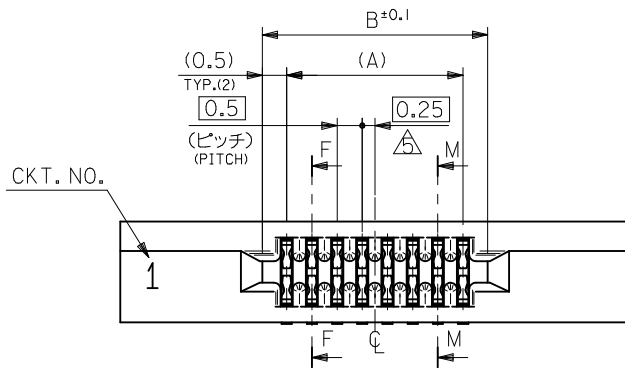
6.

R0.3は、FPCの導体部にかからないこと。

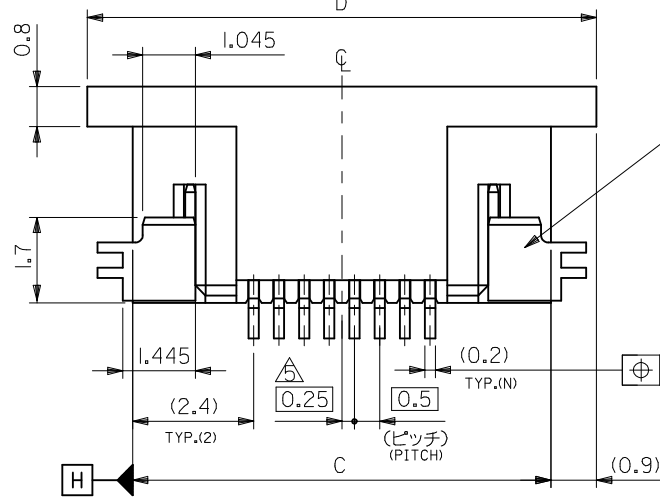
R0.3 MUST NOT BE OVER LAPPED TO PATTERN OF FPC.

7. ELV及びRoHS適合品

ELV AND RoHS COMPLIANT



3. 金具
FITTING NAIL



0.2 H

RELEASED EC NO: J2013-1014 DRAWN: TMORISHITA 2012/09/07 CHKD: KTAKAHASHI 2012/09/10 APPR: KMORIKAWA 2013/03/15	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY TMORISHITA	DATE 2012/09/07	TITLE 0.5 FPC CONN NON-ZIF R/A HOUSING ASSY				
		10 OVER 30 UNDER	± 0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/10					
		30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO. SD-52689-049				SHEET NO. 1 OF 2
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART							
	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					